## 2SD2374A

## Silicon NPN triple diffusion planar type

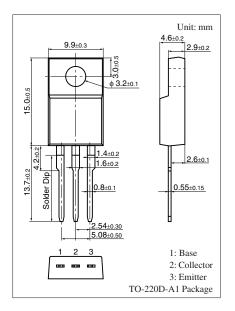
For power amplification Complementary to 2SB1548A

#### ■ Features

- High forward current transfer ratio h<sub>FE</sub> which has satisfactory linearity
- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Full-pack package which can be installed to the heat sink with one screw

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Symbol	Rating	Unit	
n) V <sub>CBO</sub>	80	V	
n) V <sub>CEO</sub>	80	V	
n) V <sub>EBO</sub>	6	V	
$I_{C}$	3	A	
$I_{CP}$	5	A	
C P <sub>C</sub>	25	W	
	2.0		
T <sub>j</sub>	150	°C	
$T_{stg}$	-55 to +150	°C	
ei	en) V <sub>CBO</sub> en) V <sub>CEO</sub> en) V <sub>EBO</sub> I <sub>C</sub> I <sub>CP</sub> 5°C P <sub>C</sub>	en) V <sub>CBO</sub> 80 en) V <sub>CEO</sub> 80 en) V <sub>EBO</sub> 6 I <sub>C</sub> 3 I <sub>CP</sub> 5 en 25 en 7 <sub>j</sub> 150	



### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

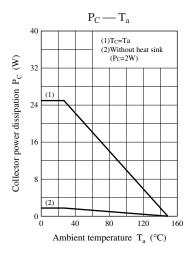
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 30 \text{ mA}, I_B = 0$	80			V
Base-emitter voltage	$V_{BE}$	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$			1.8	V
Collector-emitter cutoff current (E-B short)	I <sub>CES</sub>	$V_{CE} = 80 \text{ V}, V_{BE} = 0$			200	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 60 \text{ V}, I_{B} = 0$			300	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_{C} = 0$			1	mA
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}$	70		250	_
	h <sub>FE2</sub>	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	10			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 3 \text{ A}, I_B = 0.375 \text{ A}$			1.2	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = 1 \text{ A}, I_{B1} = 0.1 \text{ A}, I_{B2} = -0.1 \text{ A}$		0.5		μs
Storage time	t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$		2.5		μs
Fall time	$t_{\rm f}$			0.4		μs

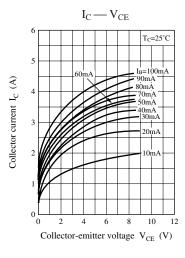
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$ 

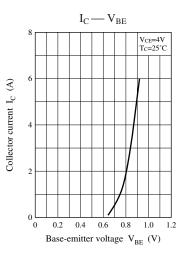
#### 2. \*: Rank classification

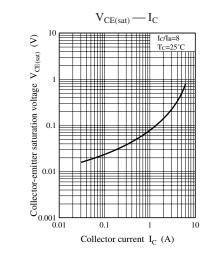
Rank	Q	Р
$h_{FE1}$	70 to 150	120 to 250

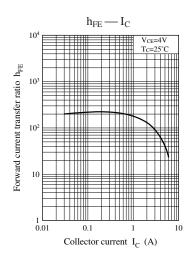
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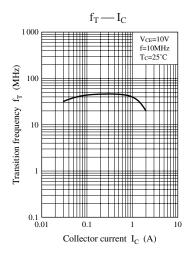


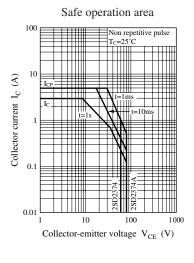


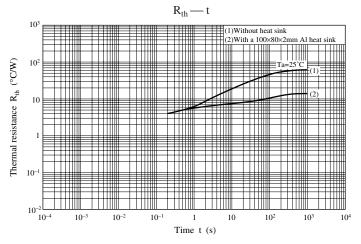












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